

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of Docket No: Q78432  
Hien Boon TAN, et al.  
Appln. No.: 10/721,382 Group Art Unit: 2894  
Confirmation No.: 6007 Examiner: David E. Graybill  
Filed: November 26, 2003  
For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF  
MANUFACTURING

**PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of one month, extending the time for responding to the Final Office Action dated October 10, 2008 to February 10, 2009.

The USPTO is directed and authorized to charge the statutory fee of \$130.00 and all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

  
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Date: February 6, 2009